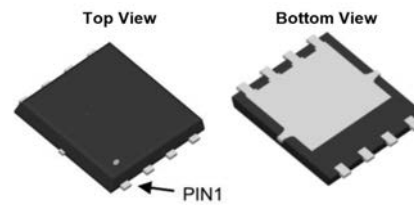


Features

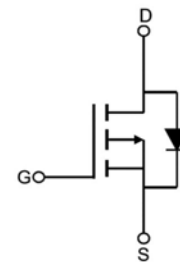
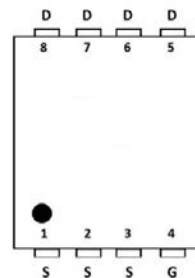
- $V_{DS} = -30V$, $I_D = -80A$
 $R_{DS(ON)} \text{ TYP.} = 3.9m\Omega @ V_{GS} = -10V$
 $R_{DS(ON)} \text{ TYP.} = 5.4m\Omega @ V_{GS} = -4.5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead free product is acquired



PDFN5x6-8L

Application

- PWM Applications
- Load Switch
- Power Management



Absolute Maximum Ratings (@ $T_C = 25^\circ C$ unless otherwise specified)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-to-Source Voltage	-30	V
V_{GS}	Gate-to-Source Voltage	± 20	V
I_D	Continuous Drain Current	$T_C = 25^\circ C$	-80
		$T_C = 100^\circ C$	-57
I_{DM}	Pulsed Drain Current ⁽¹⁾	320	A
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾	363	mJ
P_D	Power Dissipation	$T_C = 25^\circ C$	52
		$T_C = 100^\circ C$	21
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150	$^\circ C$

Thermal Characteristics

Symbol	Parameter	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽³⁾	43	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance, Junction to Case	2.4	

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = -250\mu\text{A}, V_{GS} = 0\text{V}$	-30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -30\text{V}, V_{GS} = 0\text{V}$	-	-	-1.0	μA
I_{GSS}	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-1.2	-1.7	-2.2	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽⁴⁾	$V_{GS} = -10\text{V}, I_D = -20\text{A}$	-	3.9	5.9	$\text{m}\Omega$
		$V_{GS} = -4.5\text{V}, I_D = -10\text{A}$	-	5.4	8.0	$\text{m}\Omega$
Dynamic Characteristics						
R_g	Gate Resistance	$f = 1\text{MHz}$	-	3.9	-	Ω
C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = -15\text{V},$ $f = 1\text{MHz}$	-	7747	-	pF
C_{oss}	Output Capacitance		-	871	-	pF
C_{rss}	Reverse Transfer Capacitance		-	559	-	pF
Q_g	Total Gate Charge	$V_{GS} = 0 \text{ to } -10\text{V}$ $V_{DS} = -15\text{V}, I_D = -20\text{A}$	-	121	-	nC
Q_{gs}	Gate Source Charge		-	23	-	nC
Q_{gd}	Gate Drain("Miller") Charge		-	18	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-On DelayTime	$V_{GS} = -10\text{V}, V_{DD} = -15\text{V}$ $I_D = -20\text{A}, R_{GEN} = 3\Omega$	-	28	-	ns
t_r	Turn-On Rise Time		-	83	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	77	-	ns
t_f	Turn-Off Fall Time		-	66	-	ns
Body Diode Characteristics						
I_S	Maximum Continuous Body Diode Forward Current		-	-	-80	A
I_{SM}	Maximum Pulsed Body Diode Forward Current		-	-	-320	A
V_{SD}	Body Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = -30\text{A}$	-		1.2	V
t_{rr}	Body Diode Reverse Recovery Time	$I_F = -20\text{A}, di/dt = 100\text{A}/\mu\text{s}$	-	30	-	ns
Q_{rr}	Body Diode Reverse Recovery Charge		-	19.5	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting $T_J = 25^\circ\text{C}$, $V_{DD} = -15\text{V}$, $V_G = -10\text{V}$, $R_G = 25\text{ohm}$, $L = 0.5\text{mH}$, $I_{AS} = -38.08\text{A}$, $V_{DD} = 0\text{V}$ during time in avalanche.
 3. $R_{\theta JA}$ is measured with the device mounted on a 1inch^2 pad of 2oz copper FR4 PCB.
 4. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Typical Performance Characteristics

Figure 5: Output Characteristics

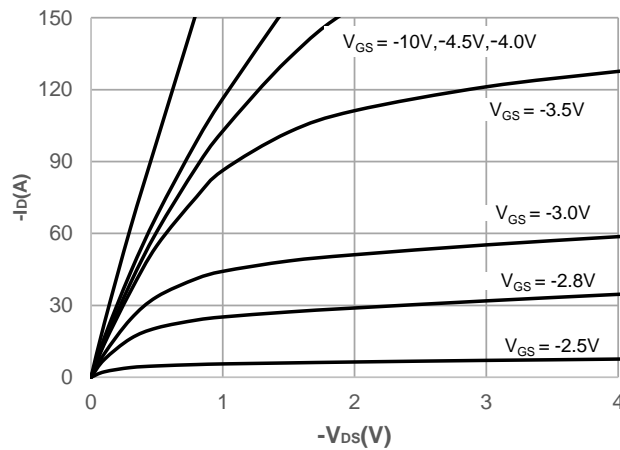


Figure 6: Typical Transfer Characteristics

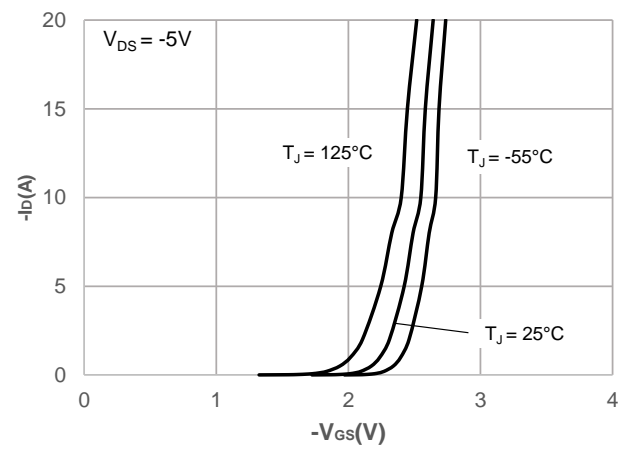


Figure 7: On-resistance vs. Drain Current

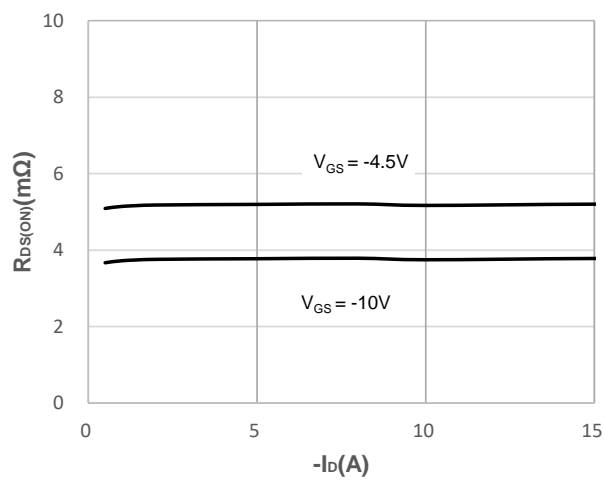


Figure 8: Body Diode Characteristics

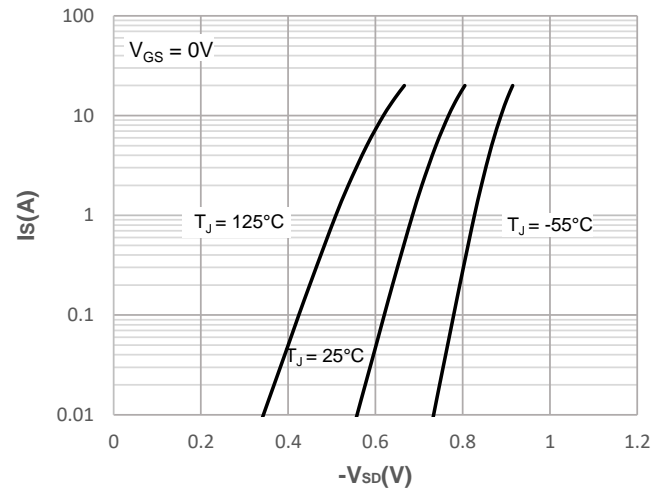


Figure 9: Gate Charge Characteristics

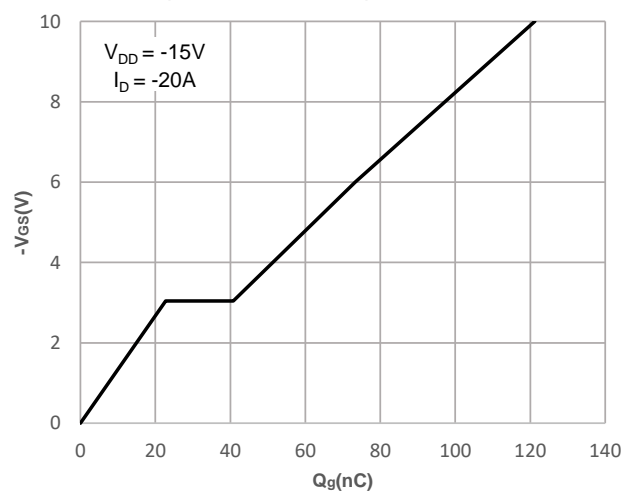
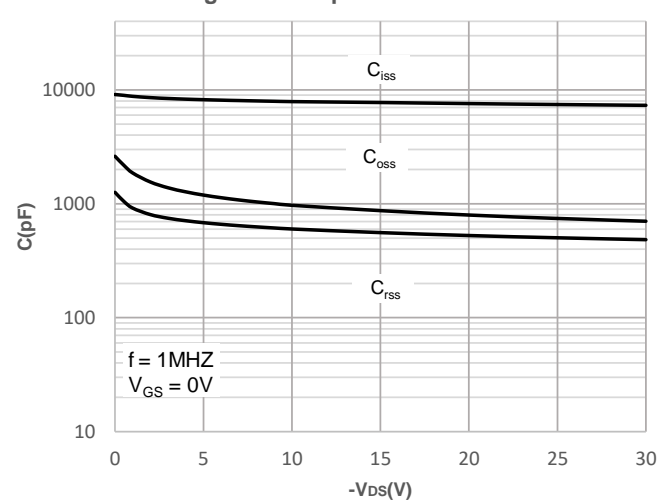


Figure 10: Capacitance Characteristics



Typical Performance Characteristics

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

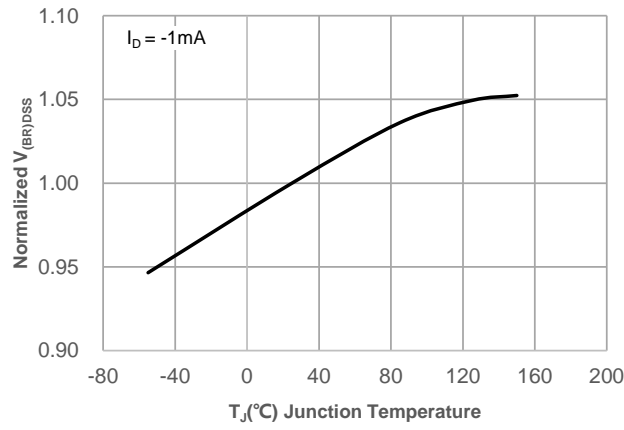


Figure 12: Normalized on Resistance vs. Junction Temperature

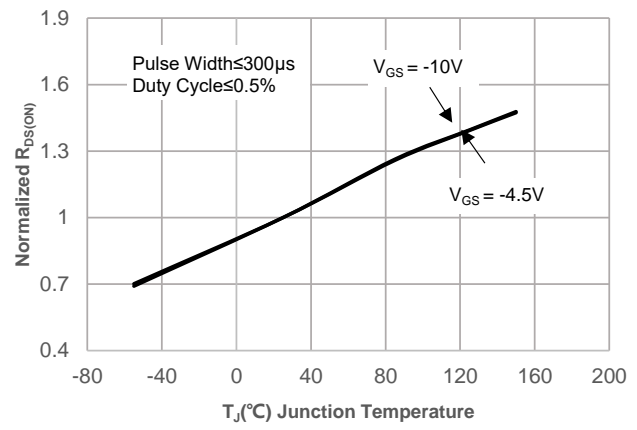


Figure 13: Normalized Threshold Voltage vs. Junction Temperature

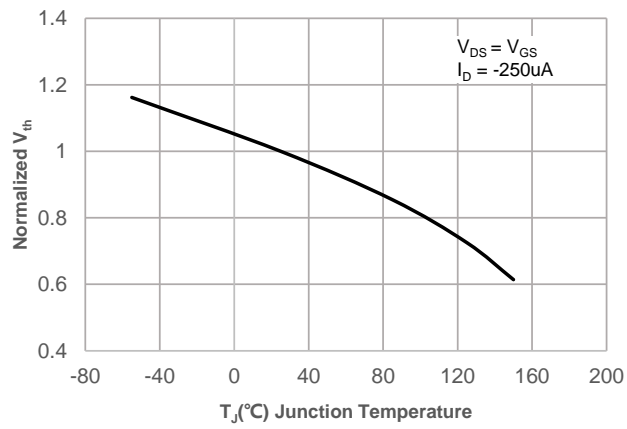


Figure 14: $R_{DS(ON)}$ vs. V_{GS}

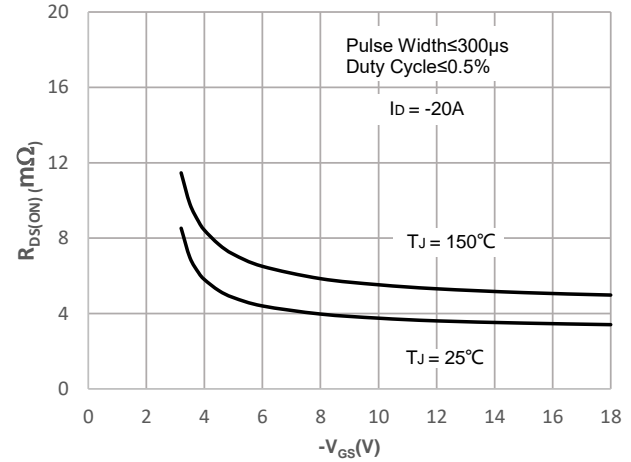
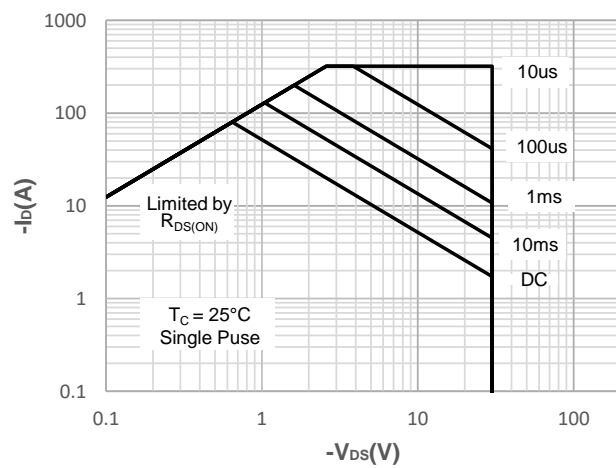


Figure 15: Maximum Safe Operating Area



Typical Performance Characteristics

Figure 1: Power De-rating

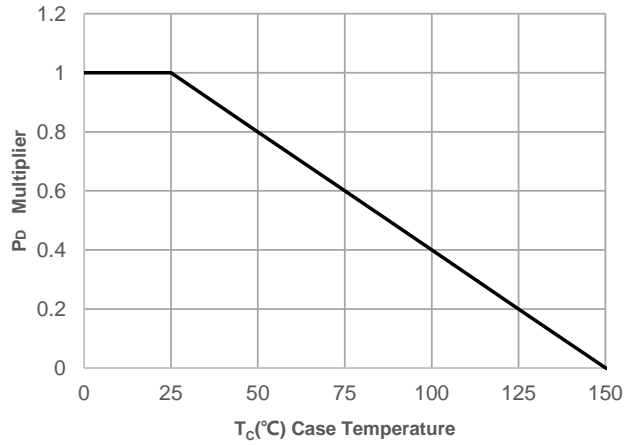


Figure 2: Current De-rating

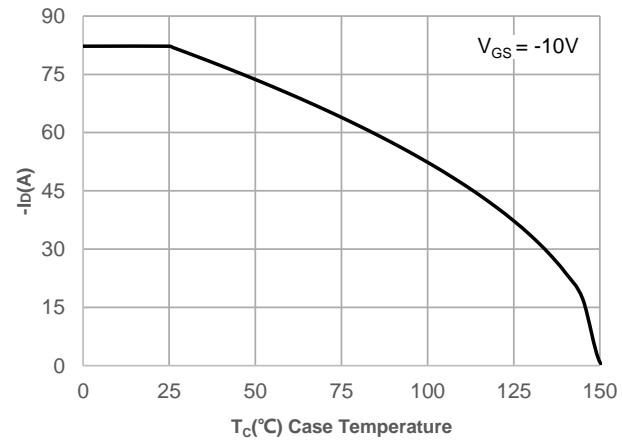


Figure 3: Normalized Maximum Transient Thermal Impedance

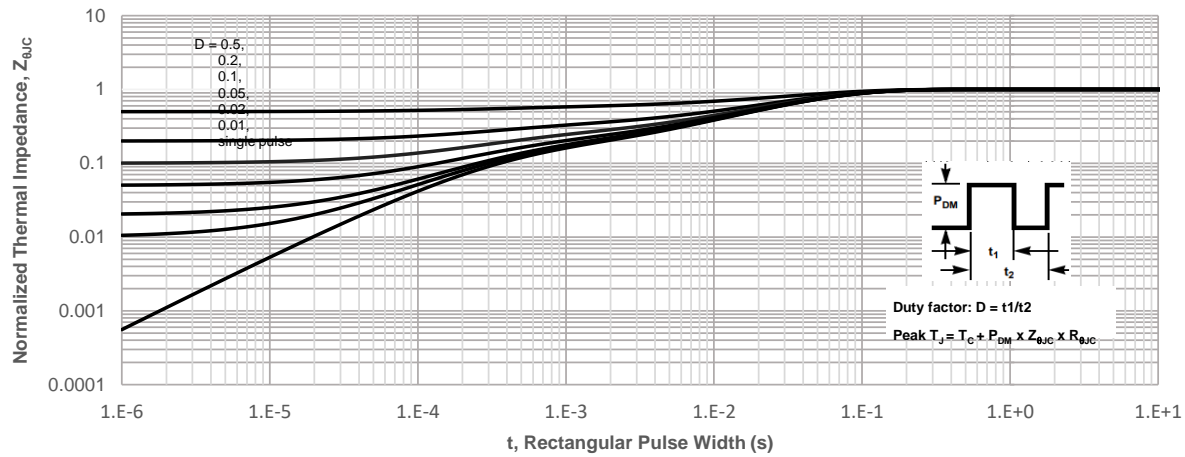
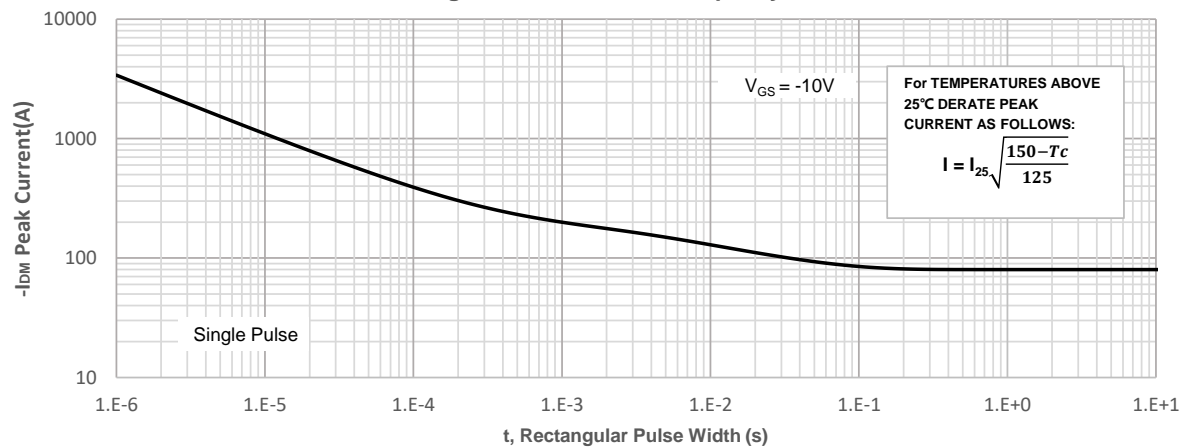


Figure 4: Peak Current Capacity



Test Circuit

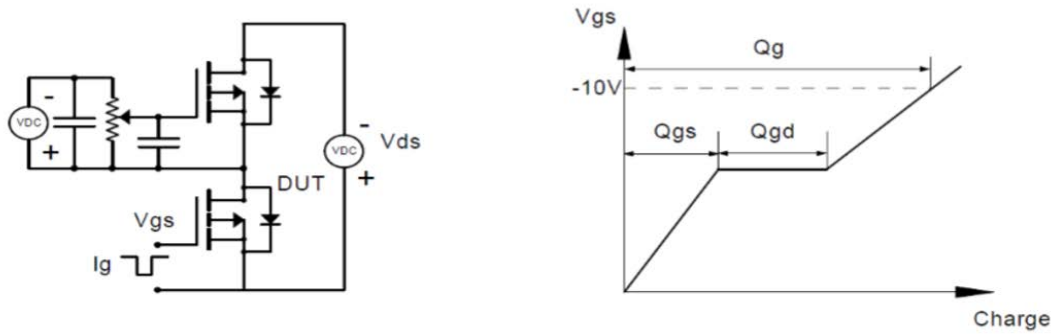


Figure 1: Gate Charge Test Circuit & Waveform

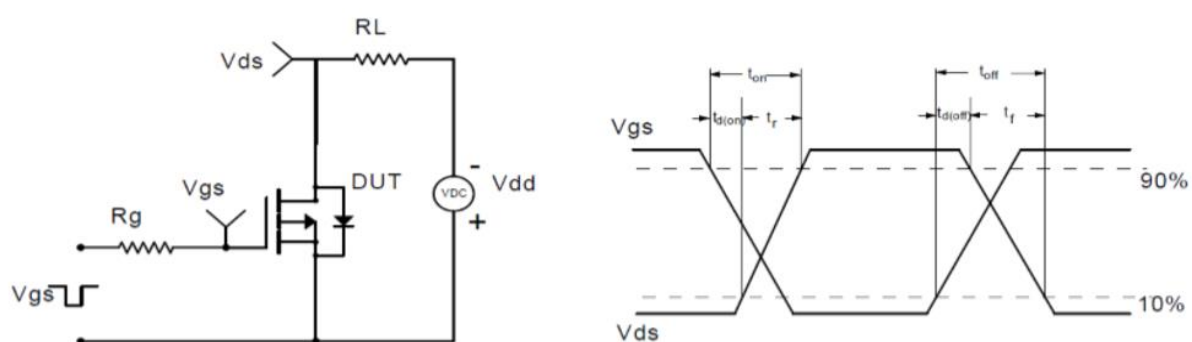


Figure 2: Resistive Switching Test Circuit & Waveform

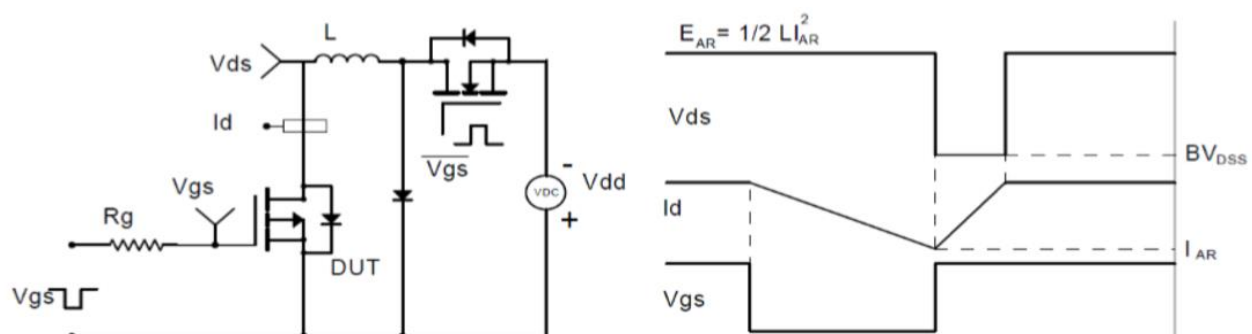


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

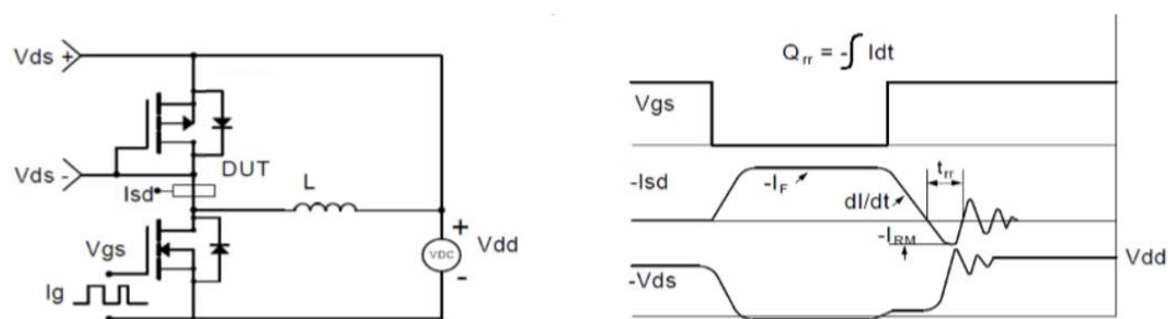
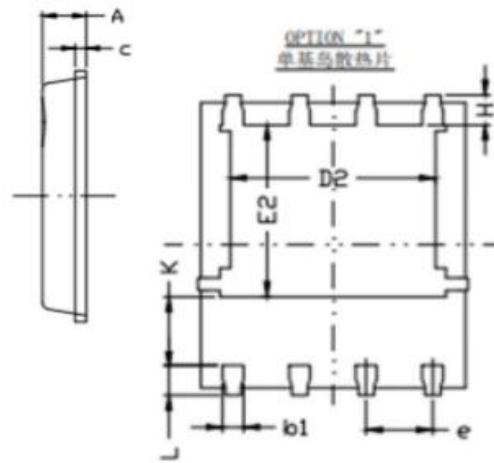
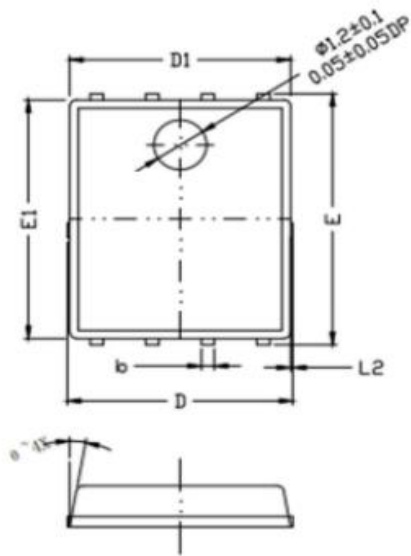


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(PDFN5X6-8L)



SYM BDL	MILLIMETER		
	MIN	NDM	MAX
A	0.90	1.00	1.10
b	0.25	0.30	0.35
b1	0.30	0.40	0.45
c	0.22	0.25	0.28
D	--	--	5.30
D1	4.90	5.05	5.20
D2	3.90 REF		
D3	1.70 REF		
E	6.00	6.15	6.30
E1	5.70	5.85	6.00
E2	3.50 REF		
e	1.10	1.27	1.40
H	0.51	0.61	0.71
K	1.10	--	--
L	0.51	0.61	0.71
L2	--	--	0.10
θ	8*	~	12*